

## FAST GATE TURN-OFF THYRISTORS

Thyristors in TO-220AB envelopes capable of being turned both on and off via the gate. They are suitable for use in high-frequency inverters, power supplies, motor control etc. The devices have no reverse blocking capability. For reverse blocking operation use with a series diode, for reverse conducting operation use with an anti parallel diode.

### QUICK REFERENCE DATA

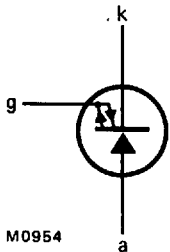
		BTV58-600R			850R	1000R	
Repetitive peak off-state voltage	$V_{DRM}$ max.	600	850	1000		V	
Non-repetitive peak on-state current	$I_{TSM}$ max.				75	A	
Controllable anode current	$I_{TCRM}$ max.				25	A	
Average on-state current	$I_{T(AV)}$ max.				10	A	
Fall time	$t_f$ max.				250	ns	

### MECHANICAL DATA

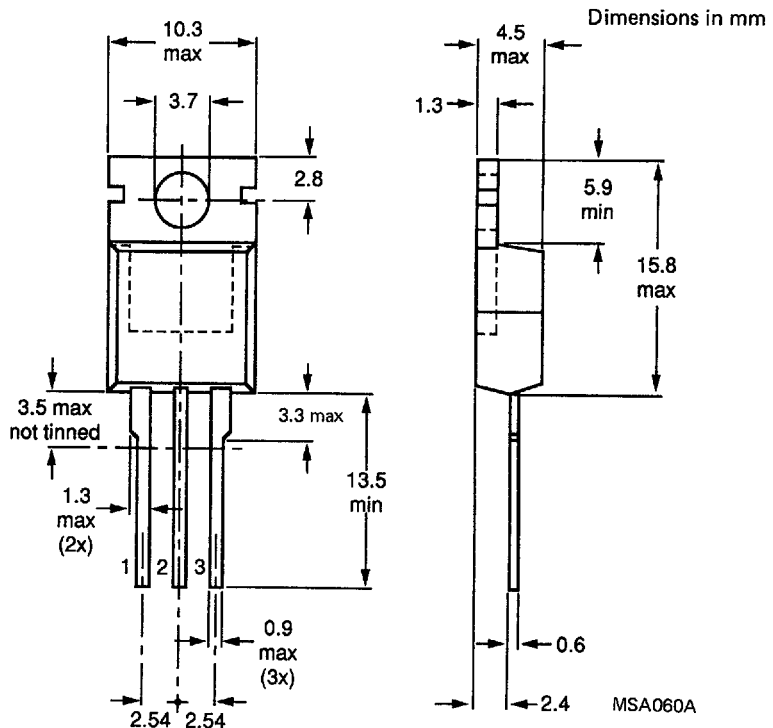
Fig.1 TO-220AB.

Pinning:

- 1 = Cathode
- 2 = Anode
- 3 = Gate



M0954



Net mass: 2 g

Note: The exposed metal mounting base is directly connected to the anode. [www.DataSheet4U.com](http://www.DataSheet4U.com)

Accessories supplied on request: see data sheets Mounting instructions and accessories for TO-220 envelopes.

# BTV58 SERIES

www.DataSheet4U.com

## RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Anode to cathode		BTV58-600R	850R	1000R
Transient off-state voltage*	$V_{DSM}$	max. 750	1000	1100 V
Repetitive peak off-state voltage*	$V_{DRM}$	max. 600	850	1000 V
Working off-state voltage*	$V_{DW}$	max. 400	600	800 V
Continuous off-state voltage*	$V_D$	max. 400	500	650 V
Average on-state current (averaged over any 20 ms period) up to $T_{mb} = 80\text{ °C}$	$I_{T(AV)}$	max.	10	A
Controllable anode current	$I_{TCRM}$	max.	25	A
Non-repetitive peak on-state current $t = 10\text{ ms}$ ; half-sinewave; $T_j = 120\text{ °C}$ prior to surge	$I_{TSM}$	max.	75	A
$I^2 t$ for fusing; $t = 10\text{ ms}$	$I^2 t$	max.	28	$A^2 s$
Total power dissipation up to $T_{mb} = 25\text{ °C}$	$P_{tot}$	max.	65	W

## Gate to cathode

Repetitive peak on-state current $T_j = 120\text{ °C}$ prior to surge gate-cathode forward; $t = 10\text{ ms}$ ; half-sinewave	$I_{GFM}$	max.	25	A
gate-cathode reverse; $t = 20\text{ }\mu s$	$I_{GRM}$	max.	25	A
Average power dissipation (averaged over any 20 ms period)	$P_{G(AV)}$	max.	2,5	W

## Temperatures

Storage temperature	$T_{stg}$		-40 to +150	$^{\circ}C$
Operating junction temperature	$T_j$	max.	120	$^{\circ}C$

## THERMAL RESISTANCE

From junction to mounting base	$R_{th\ j-mb}$	=	1,5	K/W
From mounting base to heatsink with heatsink compound	$R_{th\ mb-h}$	=	0,3	K/W
with 56367 alumina insulator and heatsink compound (clip-mounted)	$R_{th\ mb-h}$	=	0,8	K/W

www.DataSheet4U.com

## CHARACTERISTICS

## Anode to cathode

On-state voltage

$I_T = 5 \text{ A}; I_G = 0.2 \text{ A}; T_j = 120 \text{ }^\circ\text{C}$

$V_T < 1.8 \text{ V}^*$

Rate of rise of off-state voltage that will not trigger any off-state device; exponential method

$V_D = 2/3 V_{Dmax}; V_{GR} = 5 \text{ V}; T_j = 120 \text{ }^\circ\text{C}$

$dV_D/dt < 10 \text{ kV}/\mu\text{s}$

Rate of rise of off-state voltage that will not trigger any device following conduction, linear method

$I_T = 5 \text{ A}; V_D = V_{DRMmax}; V_{GR} = 10 \text{ V}; T_j = 120 \text{ }^\circ\text{C}$

$dV_D/dt < 1.5 \text{ kV}/\mu\text{s}$

Off-state current

$V_D = V_{Dmax}; T_j = 120 \text{ }^\circ\text{C}$

$I_D < 3.0 \text{ mA}$

Latching current;  $T_j = 25 \text{ }^\circ\text{C}$ 

$I_L \text{ typ. } 1.0 \text{ A}^{**}$

## Gate to cathode

Voltage that will trigger all devices

$V_D = 12 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$

$V_{GT} > 1.5 \text{ V}$

Current that will trigger all devices

$V_D = 12 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$

$I_{GT} > 200 \text{ mA}$

Minimum reverse breakdown voltage

$I_{GR} = 1.0 \text{ mA}$

$V_{(BR)GR} > 10 \text{ V}$

## Switching characteristics (resistive load)

Turn-on when switched to  $I_T = 5 \text{ A}$  from  $V_D = 250 \text{ V}$ 

$I_{GF} = 0.5 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$

delay time

$t_d < 0.25 \text{ } \mu\text{s}$

rise time

$t_r < 1.0 \text{ } \mu\text{s}$

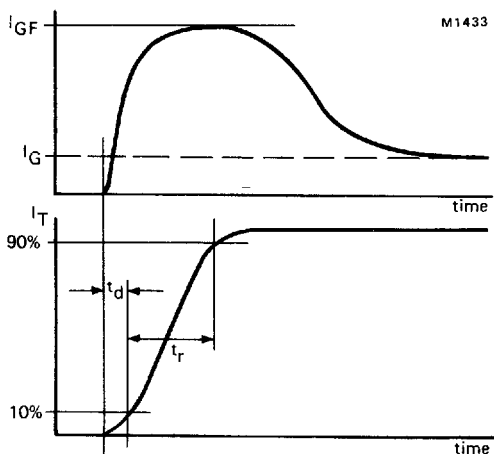


Fig.2 Waveforms

\* Measured under pulse conditions to avoid excessive dissipation.

\*\* Below latching level the device behaves like a transistor with a gain dependent on current.

**Switching characteristics (inductive load)**

Turn-off when switched from  $I_T = 5 \text{ A}$  to  $V_D = V_{Dmax}$ :

$V_{GR} = 10 \text{ V}$ ;  $L_G \leq 1.0 \mu\text{H}$ ;  $L_S \leq 0.25 \mu\text{H}$ ;  $T_j = 25 \text{ }^\circ\text{C}$

storage time

$t_s < 0.5 \mu\text{s}$

fall time

$t_f < 0.25 \mu\text{s}$

peak reverse gate current

$I_{GR} < 6 \text{ A}$

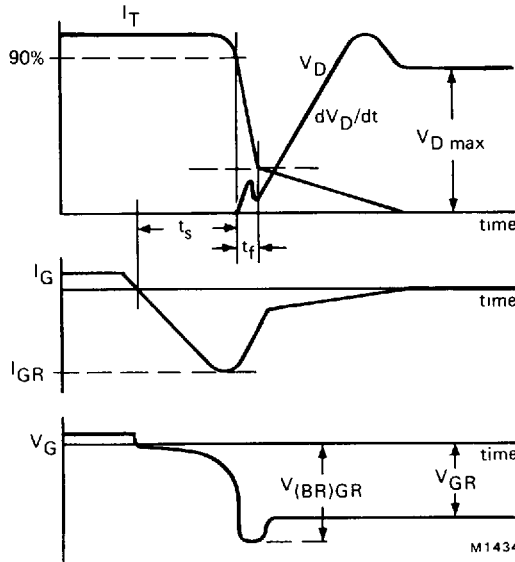


Fig.3 Waveforms.

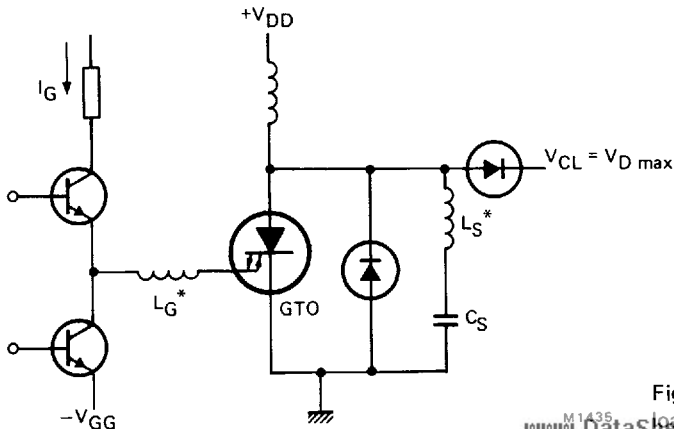


Fig.4 Inductive load test circuit.

\* indicates stray series inductance only.

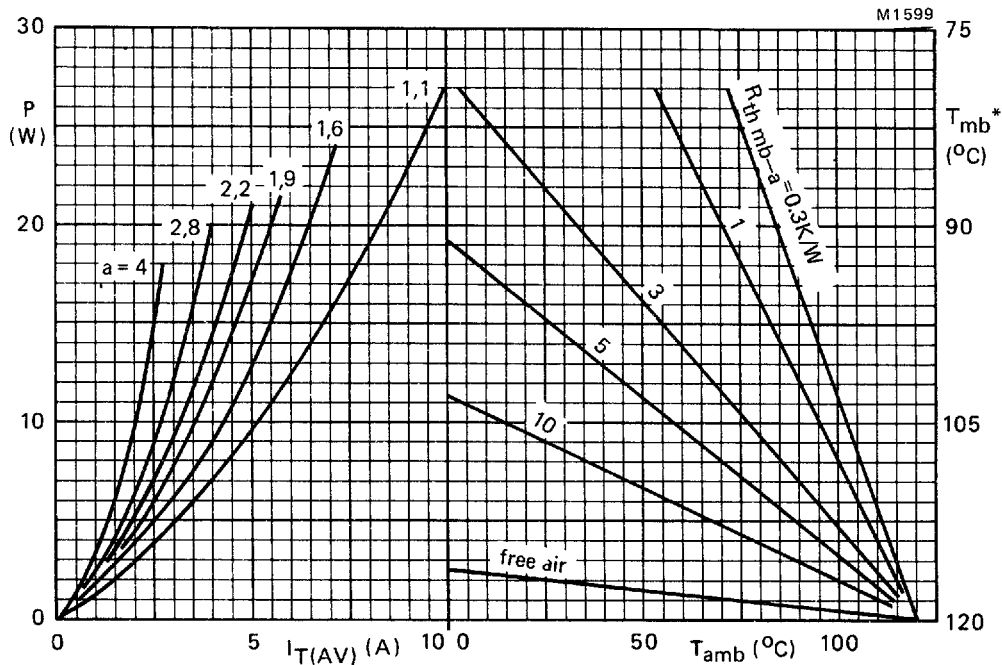


Fig.5 The right-hand part shows the interrelationship between the power (derived from the left-hand part) and the maximum permissible temperatures.

$$a = \text{form factor} = \frac{I_T(\text{RMS})}{I_T(\text{AV})}$$

P = power excluding switching losses.

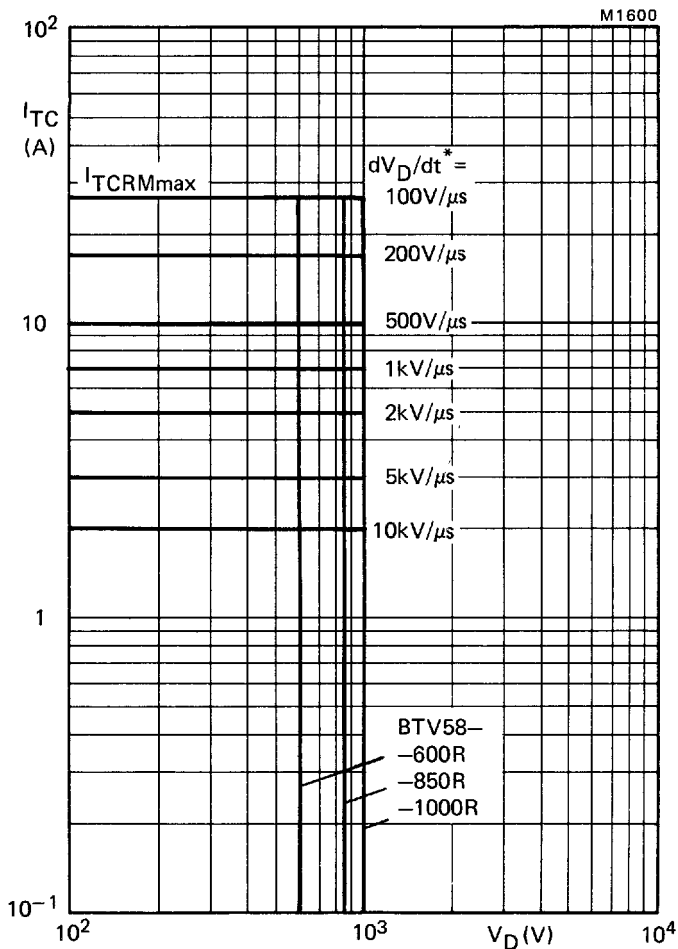


Fig.6 Anode current which can be turned off versus anode voltage; inductive load;  $V_{GR} = 10$  V;  $L_G \leq 1.0 \mu$ H;  $L_S \leq 0.25 \mu$ H;  $T_j = 85$  °C.

\* $dV_D/dt$  is calculated from  $I_T/C_S$ .

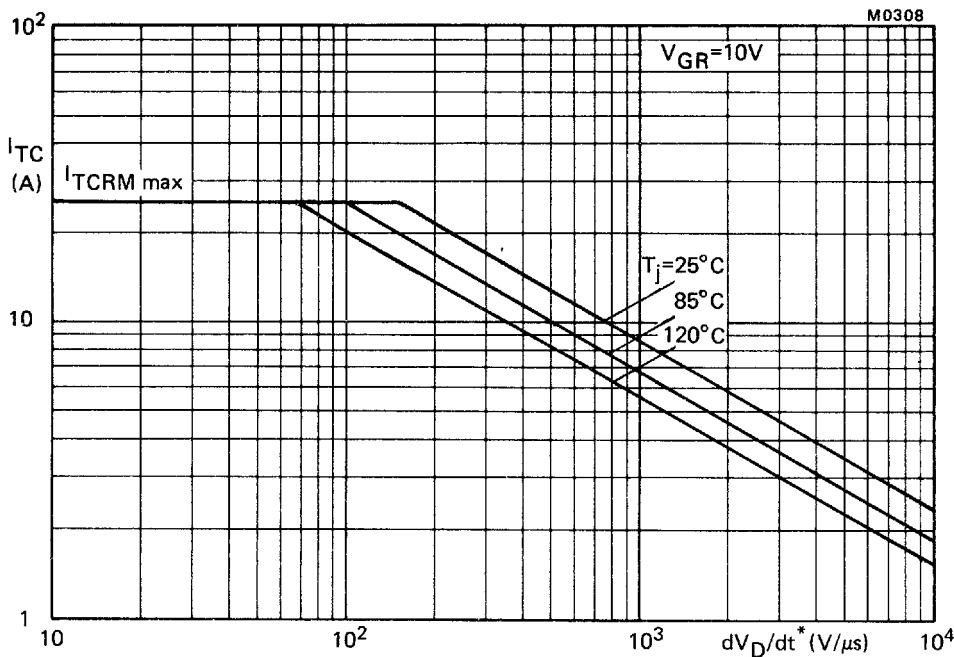


Fig.7 Anode current which can be turned off versus applied  $dV_D/dt^*$ ; inductive load;  $V_{GR} = 10\ V$ .  
 $L_G \leq 1.0\ \mu H$ ;  $L_S \leq 0.25\ \mu H$ . \* $dV_D/dt$  is calculated from  $I_T/C_S$ .

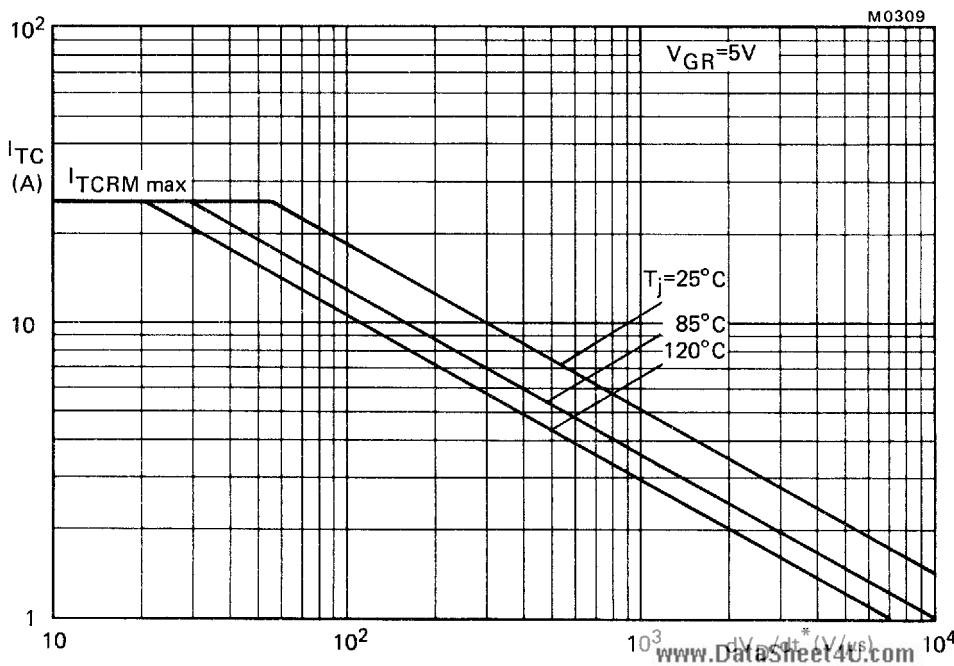


Fig.8 Anode current which can be turned off versus applied  $dV_D/dt^*$ ; inductive load;  $V_{GR} = 5\ V$ .  
 $L_G \leq 1.0\ \mu H$ ;  $L_S \leq 0.25\ \mu H$ ; \* $dV_D/dt$  is calculated from  $I_T/C_S$ .

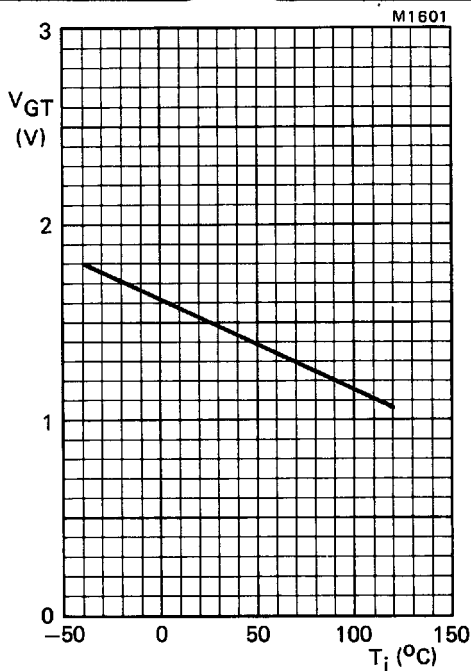


Fig.9 Minimum gate voltage that will trigger all devices as a function of junction temperature;  $V_D = 12$  V.

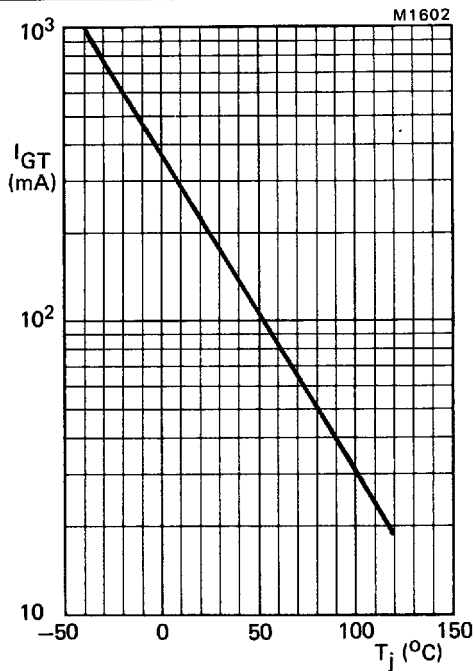


Fig.10 Minimum gate current that will trigger all devices as a function of junction temperature;  $V_D = 12$  V.

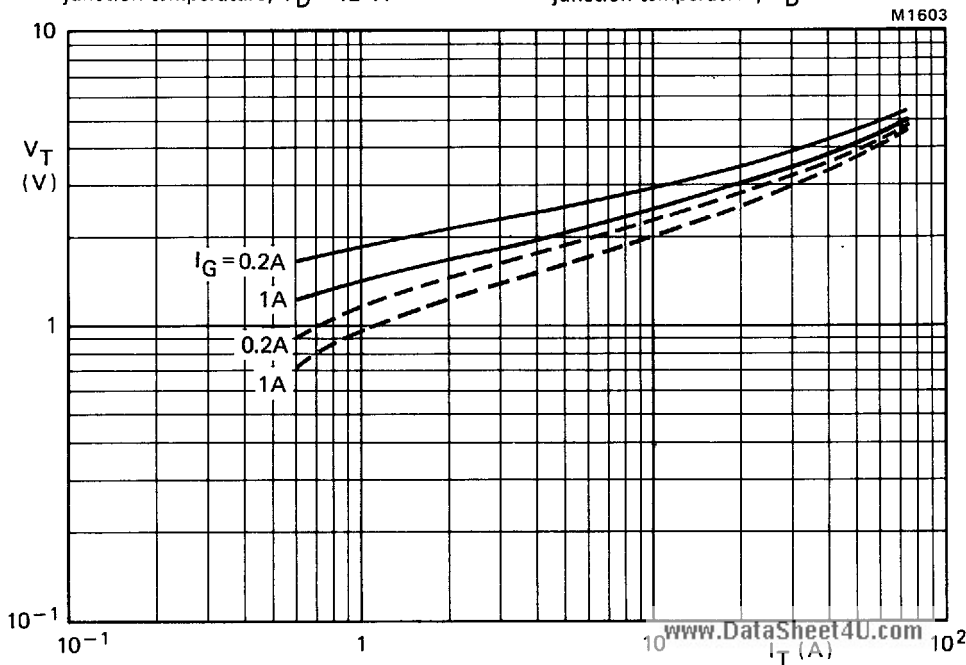


Fig.11 Maximum  $V_T$  versus  $I_T$ ; ———  $T_j = 25$   $^{\circ}\text{C}$ ; - - - -  $T_j = 120$   $^{\circ}\text{C}$ .



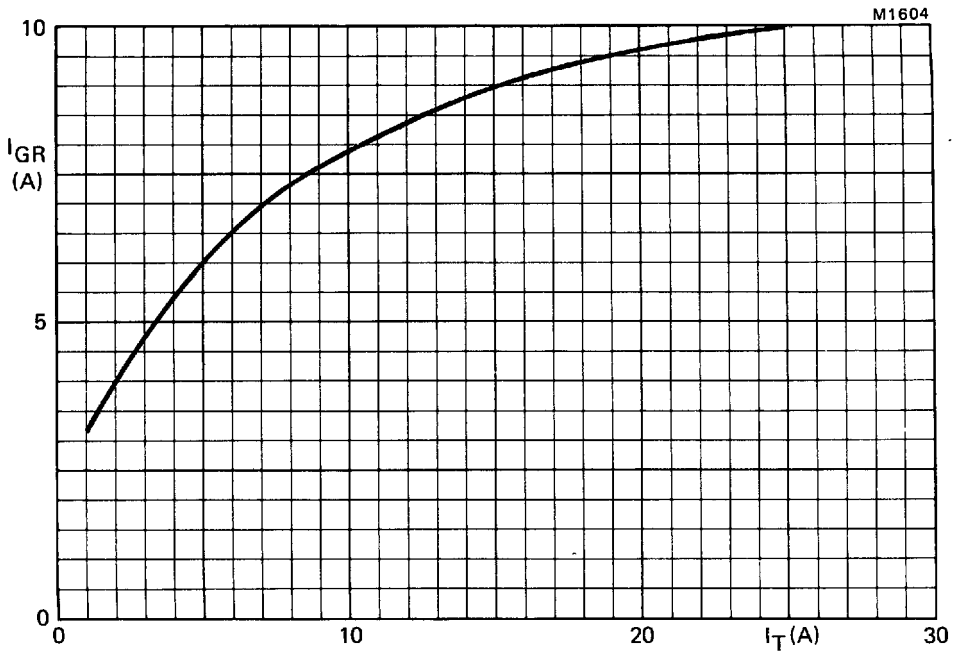


Fig. 12 Peak reverse gate current versus anode current at turn-off; inductive load;  $V_{GR} = 10$  V;  $I_G = 0.2$  A;  $L_G = 0.8$   $\mu$ H;  $T_j = 120$   $^{\circ}$ C; maximum values.

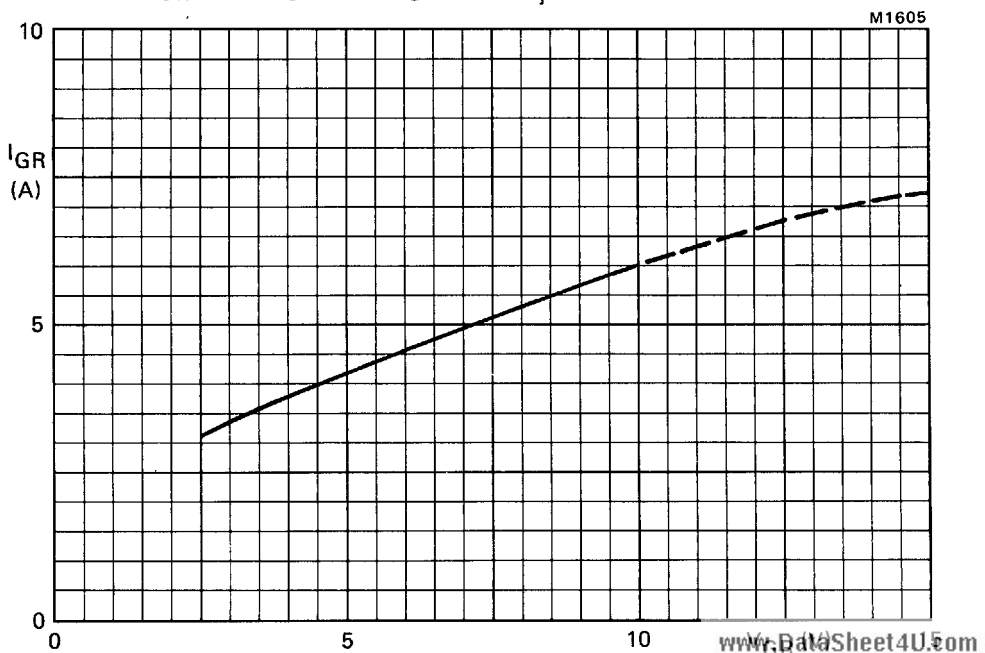


Fig. 13 Peak reverse gate current versus applied reverse gate voltage; inductive load;  $I_T = 5$  A;  $I_G = 0.2$  A;  $L_G = 0.8$   $\mu$ H;  $T_j = 120$   $^{\circ}$ C; maximum values.

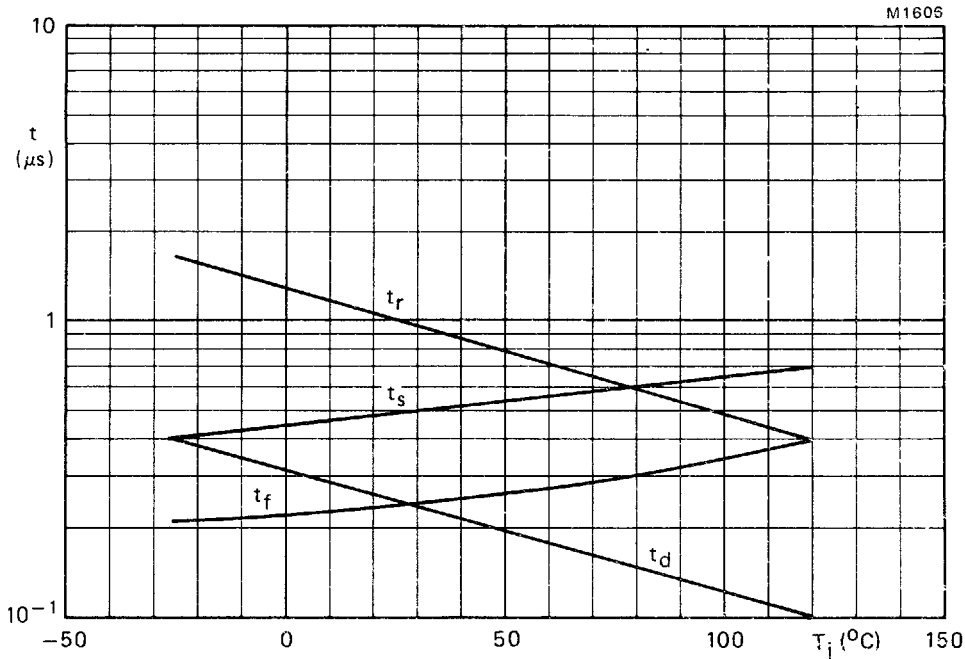


Fig.14 Switching times as a function of junction temperature;  $V_D \geq 250$  V;  $I_T = 5$  A;  $I_{GF} = 0.5$  A;  $V_{GR} = 10$  V;  $I_G = 0.2$  A;  $L_G = 0.8 \mu\text{H}$ ; maximum values.

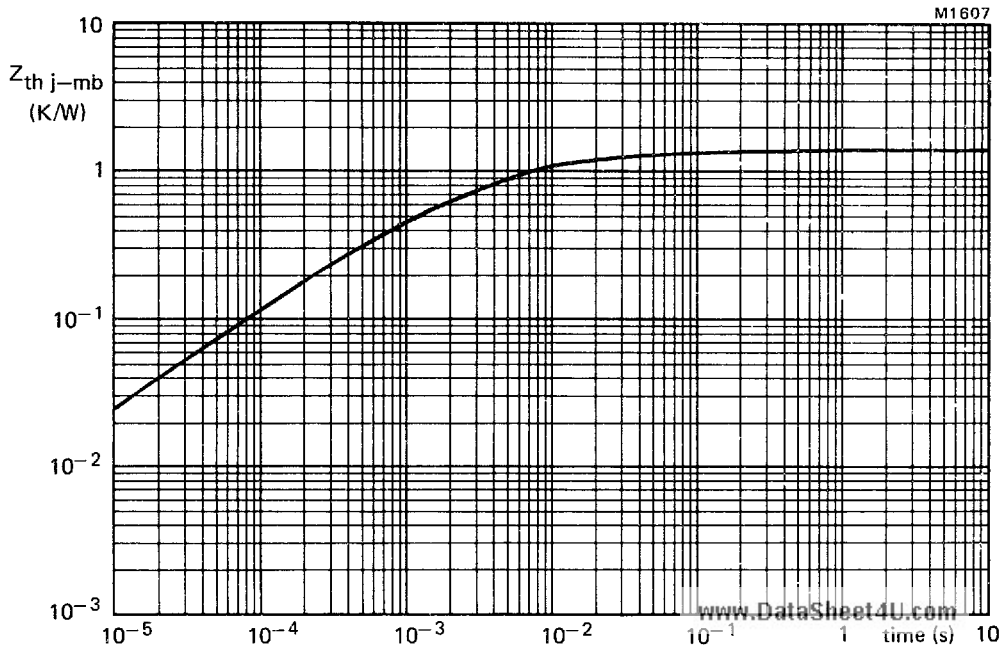


Fig.15 Transient thermal impedance.

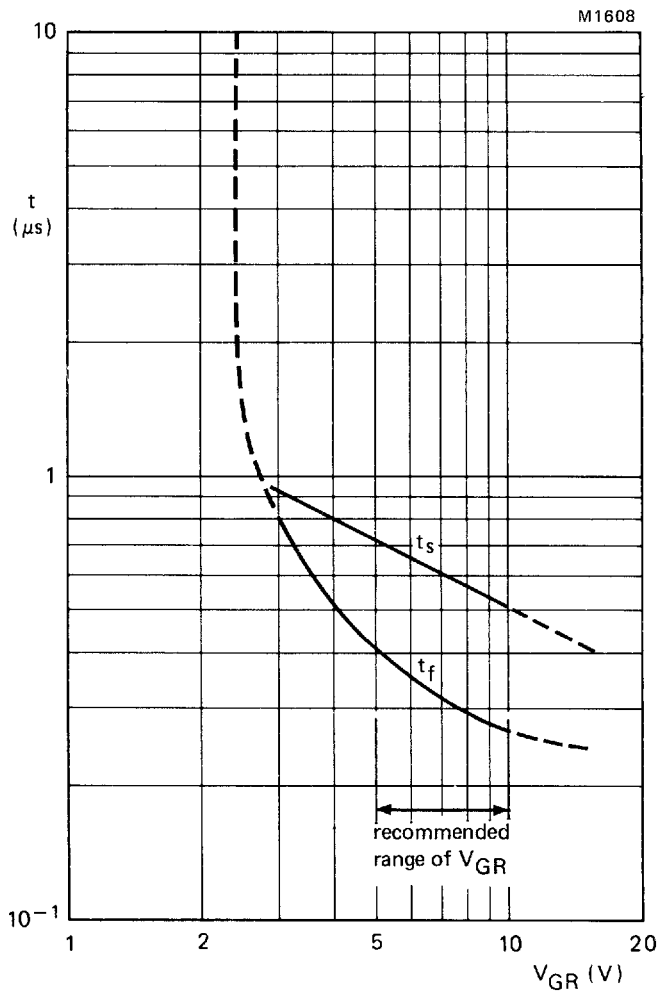


Fig. 16 Storage and fall times versus applied reverse gate voltage; inductive load;  $I_T = 5$  A;  $I_G = 0.2$  A;  $L_G = 0.8 \mu H$ ;  $T_j = 25^\circ C$ ; maximum values.

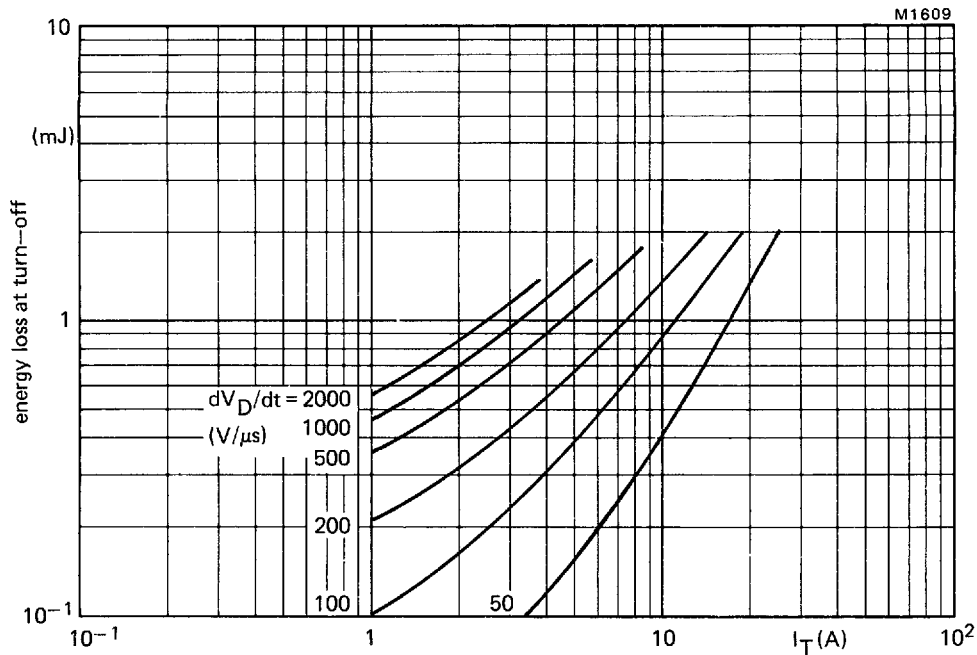


Fig.17 Maximum energy loss at turn-off (per cycle) as a function of anode current and applied  $dV_D/dt$  (calculated from  $I_T/C_S$ );  $dV_D/dt$  linear up to  $V_{Dmax} = 600$  V;  $V_{GR} = 10$  V;  $I_G = 0.2$  A;  $L_G \leq 1.0 \mu H$ ;  $L_S \leq 0.25 \mu H$ ;  $T_j = 120$  °C.

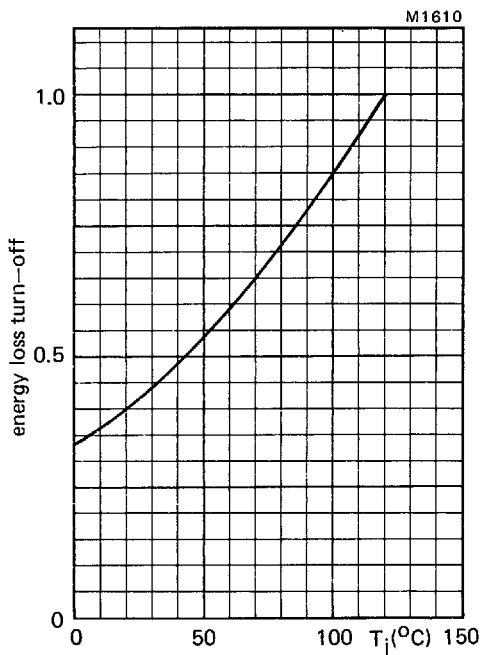


Fig.18 Energy loss vs junction temperature;  $I_G = 0.2$  A;  $V_{GR} = 10$  V. Normalised to  $T_j = 120$  °C.